



## Product/Process Change Notice - PCN 13\_0303 Rev. -

Analog Devices, Inc. Three Technology Way Norwood, Massachusetts 02062-9106

This notice is to inform you of a change that will be made to certain ADI products (see Material Report). Any issues with this PCN or requirements to qualify the change (additional data or samples) must be sent to ADI within 30 days of publication date. ADI contact information is listed below.

**PCN Title:** Assembly transfer to Amkor Philippines and Test Transfer to STATS ChipPAC China of Select 5x5 LFCSP Products

**Publication Date:** 25-Nov-2013

**Effectivity Date:** 23-Feb-2014 *(the earliest date that a customer could expect to receive changed material)*

### Revision Description:

Initial Release

### Description Of Change

ADI is transferring to qualified subcontractor Amkor Philippines for assembly and to subcontractor STATS ChipPAC China for test of select 5x5 LFCSP products.

The die attach is changing from Ablestik 3230 to Ablestik 8290. The mold compound is changing from Sumitomo G770 to Sumitomo G700. The package outline dimensions and wire diameter of each product will be maintained. See BOM attachment for details.

### Reason For Change

ADI is transferring due to the closure of STATS ChipPAC Malaysia at the end of 2014.

ADI's assembly subcontractors manufacture products using Analog Devices specified manufacturing flows, materials, process controls and monitors, ensuring the same level of quality and reliability on products they receive from the new site.

### Impact of the change (positive or negative) on fit, form, function & reliability

The Transfer will have no impact on the form, fit, function and reliability of the devices.

### Product Identification *(this section will describe how to identify the changed material)*

The parts that will be assembled after the transfer will be identified by assembly lot and the country of origin.

### Summary of Supporting Information

Qualification has been performed per AEC-Q100, Stress Test Qualification for Integrated Circuits. See attached Qualification Report Summary. Test correlation and validation will be performed. See attached Test Plan.

### Supporting Documents

**Attachment 1: Type:** Qualification Report Summary

ADI\_PCN\_13\_0303\_Rev\_-\_Automotive Qualification Report Summary.pdf

**Attachment 2: Type:** Test Correlation Plan

**Attachment 3: Type:** Detailed Change Description

ADI\_PCN\_13\_0303\_Rev\_-\_BOM.xlsx

**For questions on this PCN, send email to the regional contacts below or contact your local ADI sales representative**

**Americas:** [PCN\\_Americas@analog.com](mailto:PCN_Americas@analog.com)

**Europe:** [PCN\\_Europe@analog.com](mailto:PCN_Europe@analog.com)

**Japan:** [PCN\\_Japan@analog.com](mailto:PCN_Japan@analog.com)

**Rest of Asia:** [PCN\\_ROA@analog.com](mailto:PCN_ROA@analog.com)

**Appendix A - Affected ADI Models****Added Parts On This Revision - Product Family / Model Number (30)**

ADV7180 / AD55/055Z-0	ADV7180 / AD55/055Z-0RL	ADV7180 / ADV7180BCP3Z	ADV7180 / ADV7180BCP3Z-RL	ADV7180 / ADV7180KCP3Z
ADV7180 / ADV7180KCP3Z-RL	ADV7182 / ADV7182WBCPZ	ADV7182 / ADV7182WBCPZ-RL	ADV7280 / ADV7280BCPZ	ADV7280 / ADV7280BCPZ-M
ADV7280 / ADV7280BCPZ-M-RL	ADV7280 / ADV7280BCPZ-RL	ADV7280 / ADV7280KCPZ	ADV7280 / ADV7280KCPZ-M	ADV7280 / ADV7280KCPZ-M-RL
ADV7280 / ADV7280KCPZ-RL	ADV7280 / ADV7280WBCPZ	ADV7280 / ADV7280WBCPZ-M	ADV7280 / ADV7280WBCPZ-M-RL	ADV7280 / ADV7280WBCPZ-RL
ADV7281 / ADV7281WBCPZ	ADV7281 / ADV7281WBCPZ-M	ADV7281 / ADV7281WBCPZ-M-RL	ADV7281 / ADV7281WBCPZ-MA	ADV7281 / ADV7281WBCPZ-MA-RL
ADV7281 / ADV7281WBCPZ-RL	ADV7282 / ADV7282WBCPZ	ADV7282 / ADV7282WBCPZ-M	ADV7282 / ADV7282WBCPZ-M-RL	ADV7282 / ADV7282WBCPZ-RL

**Appendix B - Revision History**

<b>Rev</b>	<b>Publish Date</b>	<b>Effectivity Date</b>	<b>Rev Description</b>
Rev. -	25-Nov-2013	23-Feb-2014	Initial Release

Analog Devices, Inc.

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